

## PACKAGED MICROELECTRONIC COMPONENT ASSEMBLIES

### ABSTRACT OF THE DISCLOSURE

Various aspects of the present invention provide microelectronic component assemblies and methods for packaging such assemblies. In one example, a microelectronic component assembly includes a substrate and a microelectronic component. This substrate has a recess in its back face and a communication opening extending through a base of the recess. This microelectronic component has an active face positioned within the substrate recess, a back face positioned outside the substrate recess, and a plurality of component contacts carried by the component active face and electrically coupled to the substrate contacts through the communication opening. This exemplary microelectronic component assembly may also include a mold compound which encapsulates the microelectronic component and a portion of the substrate active face. The mold compound may also substantially fill a gap between the periphery of the microelectronic component and a sidewall of the recess.

### FIGURE 1



\*G00002\*



\*162162\*